Slotted Optical Switch

OPB855



Features:

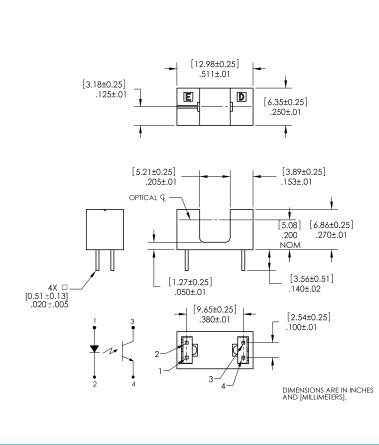
- Low profile 0.27" (6.86 mm) overall height
- Printed PCBoard mounting
- 0.205" (5.21 mm) wide and 0.220 (5.59 mm) deep slot
- 0.380" (9.65 mm) lead spacing
- Opaque plastic housing

Description:

The OPB855 slotted optical switch consists of an infrared emitting diode and a NPN silicon phototransistor, mounted on opposite sides of a 0.205" (5.21 mm) wide slot in an inexpensive plastic housing. Switching of the phototransistor occurs whenever an opaque object passes through the slot.

Applications:

- Non-contact interruptive object sensing
- Assembly line automation
- Machine automation
- Equipment security
- Machine safety



Pin #	Description				
1	Anode				
2	Cathode				
3	Collector				
4	Emitter				

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General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

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Electronics

OPB855

Electrical Specifications

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Storage & Operating Temperature Range	-40°C to +85° C			
Lead Soldering Temperature [1/16 inch (1.6mm) from the case for 5 sec. with soldering iron] $^{(1)}$	260° C			
nput Diode (See OP140 for additional information)				
Forward DC Current	50 mA			
Peak Forward Current (1 μs pulse width, 300 pps)	1 A			
Reverse DC Voltage	2 V			
Power Dissipation ⁽²⁾	100 mW			
Dutput Phototransistor (See OP550 for additional information)				
Collector-Emitter Voltage	30 V			
Emitter-Collector Voltage	5 V			
Collector DC Current	30 mA			
Power Dissipation ⁽²⁾	100 mW			

Electrical Characteristics (T_A = 25°C unless otherwise noted)

MBOL	PARAMETER	MIN	ТҮР	MAX	UNITS	TEST CONDITIONS
ıt Diode	2					
$V_{\rm F}$	Forward Voltage	-	1.30	1.80	V	I _F = 20 mA
I _R	Reverse Current	-	-	100	μA	$V_R = 2 V$
put Pho	totransistor			•	•	
		20				
(BR)CEO	Collector-Emitter Breakdown Voltage	30	-	-	V	$I_c = 1 \text{ mA}$
(BR)CEO (BR)ECO	Collector-Emitter Breakdown Voltage Emitter-Collector Breakdown Voltage	5	-	-	v v	I _c = 1 mA I _E = 100 μA

V _{CE(SAT)}	Collector-Emitter Saturation Voltage	-	-	0.4	V	I _c = 400 μA, I _F = 20 mA
I _{C(ON)}	On-State Collector Current	1.50	-	20.0	mA	V _{CE} = 5 V, I _F = 20 mA

Notes:

(1) RMA flux is recommended. Duration can be extended to 10 seconds maximum when flow soldering.

(2) Derate linearly 1.67 mW/°C above 25 $^\circ$ C.

(3) Methanol or isopropanol are recommended as cleaning agents. Plastic housing is soluble in chlorinated hydrocarbons and ketones.

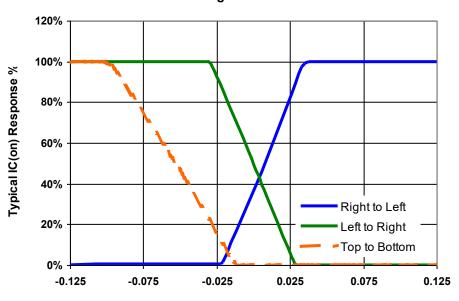
(4) All parameters tested using pulse technique.

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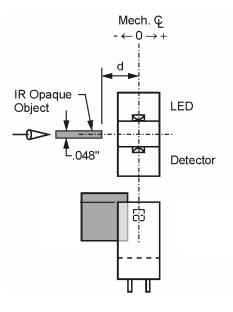




OPB855 - Flag in Middle of Slot

Displacement Distance (inches)

Test Schematic



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